

S/N 10/775,890

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Biswajit Sur et al.

Examiner: Andy Huynh

Serial No.: 10/775,890

Group Art Unit: 2818

Filed: February 9, 2004

Docket No.: 884.319US2

Title: ELECTRONIC ASSEMBLY COMPRISING SOLDERABLE THERMAL
INTERFACE AND METHODS OF MANUFACTURE

Assignee: Intel Corporation

Customer No: 21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on April 11, 2005. Please amend the above-identified patent application as follows.